

## MICROFABRICATION

### Direct Writing Laser

Manufacturer: HEIDELBERG  
INSTRUMENTS

Model: DWL66+



### General Description:

The Heidelberg DWL 66+ direct writing laser is a single wafer high resolution pattern writing equipment. Direct writing enables a high versatility and constant optimization of pattern designs. The system is equipped with a 375 nm UV laser for i-line photoresists and SU8 patterning and can achieve a minimum feature of 800 nm. Moreover, the greyscale lithography capability makes the equipment really useful in micro-optics, MEMS and MOEMS applications.

### Key Specifications:

- 375 nm, 70 mW laser source, 10 mm write head
- High resolution printing down to 800 nm
- Alignment accuracy up to 150 nm
- Back side or Front Side alignment
- Substrate size up to 200 mm diameter
- Substrate thickness up the 12 mm

<b>Availability</b>	Use allowed for all researchers with permission
<b>Location</b>	Cleanroom C5 Europastraße 12 9524 Villach
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